

• General Description

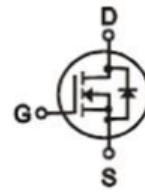
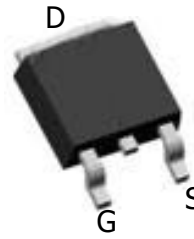
The ZM020N04D combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

• Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

• Application

- Synchronous Rectification
- Power Management in Inverter System
- POL application
- BLDC Motor driver

• Product Summary

 $V_{DS}=40V$
 $R_{DS(ON)} = 2.4m\Omega$
 $I_D=120A$


TO-252


• Ordering Information:

Part NO.	ZM020N04D
Marking	ZM020N04
Packing Information	REEL TAPE
Basic ordering unit (pcs)	2500

• Absolute Maximum Ratings ($T_C = 25^\circ C$)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	$I_D @ TC=25^\circ C$	120	A
	$I_D @ TC=75^\circ C$	91	A
	$I_D @ TC=100^\circ C$	75	A
Pulsed Drain Current ^①	I_{DM}	360	A
Total Power Dissipation($TC=25^\circ C$)	$P_D @ TC=25^\circ C$	85	W
Total Power Dissipation($TA=25^\circ C$)	$P_D @ TA=25^\circ C$	3.4	W
Operating Junction Temperature	T_J	150	$^\circ C$
Storage Temperature	T_{STG}	150	$^\circ C$
Single Pulse Avalanche Energy	E_{AS}	245	mJ
Avalanche Current	I_{AS}	70	A

●Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}	-	-	1.5	° C/W
Thermal resistance, junction - ambient	R_{thJA}	-	-	37	° C/W
Soldering temperature, wave soldering for 10s	T_{sold}	-	-	265	° C

●Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = 250\mu A$	40			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 250\mu A$	1.3		2.5	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS} = 40V, V_{GS} = 0V$			1.0	μA
Gate- Source Leakage Current	I_{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			100	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 70A$		2.4	3.1	m Ω
		$V_{GS} = 4.5V, I_D = 30A$		3	4	m Ω
Diode Forward Voltage	V_{FSD}	$I_{SD} = 20A, V_{GS} = 0V$			1.3	V

●Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C_{iss}	$V_{GS} = 0V$ $V_{DS} = 20V$ $f = 1MHz$	-	5580	-	pF
Output capacitance	C_{oss}		-	480	-	
Reverse transfer capacitance	C_{rss}		-	275	-	

●Gate Charge characteristics($T_a = 25^\circ C$)

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Total gate charge	Q_g	$V_{DD} = 20V$ $I_D = 20A$ $V_{GS} = 10V$	-	70	-	nC
Gate - Source charge	Q_{gs}		-	17	-	
Gate - Drain charge	Q_{gd}		-	12	-	

Note: ① Pulse Test : Pulse width $\leq 300\mu s$, Duty cycle $\leq 2\%$;

Fig.1 Gate-Charge Characteristics

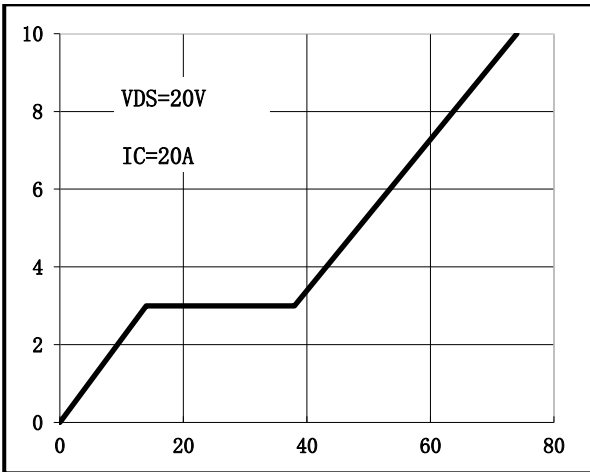


Fig.2 Capacitance Characteristics

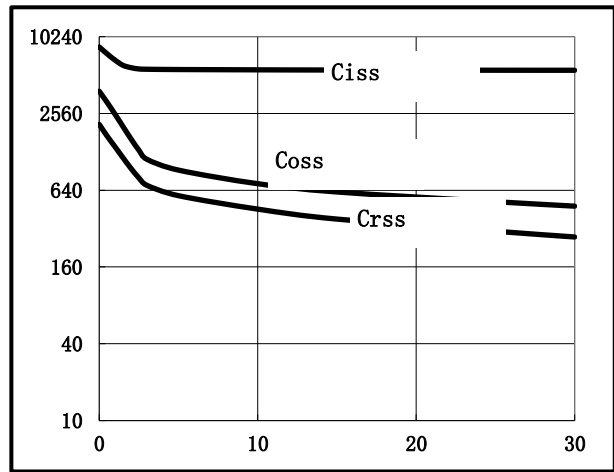


Fig.3 Power Dissipation

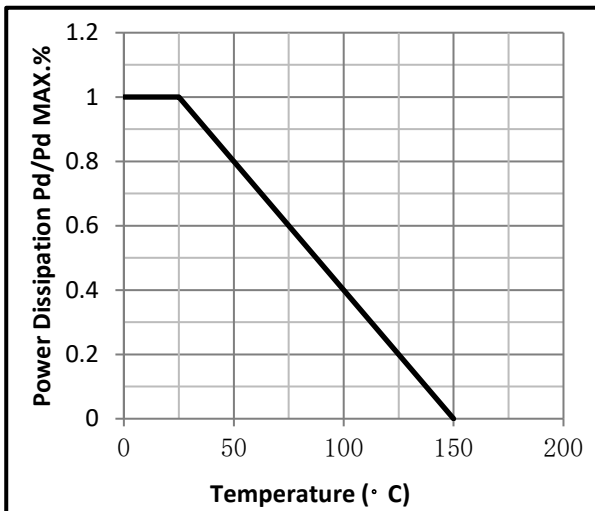


Fig.4 Typical output Characteristics

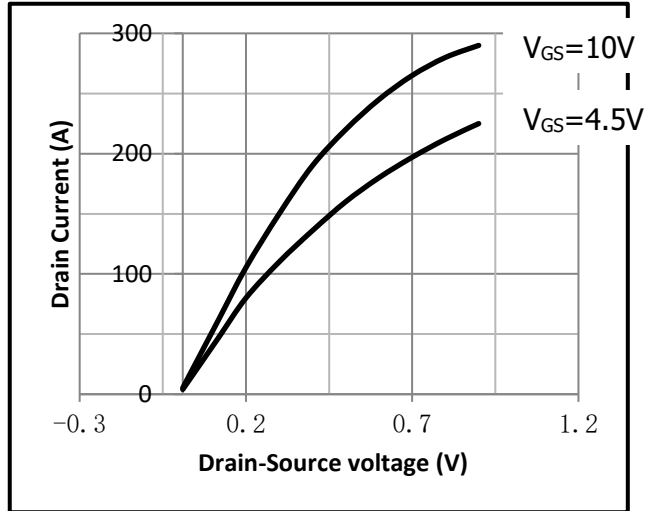


Fig.5 Threshold Voltage V.S Junction Temperature

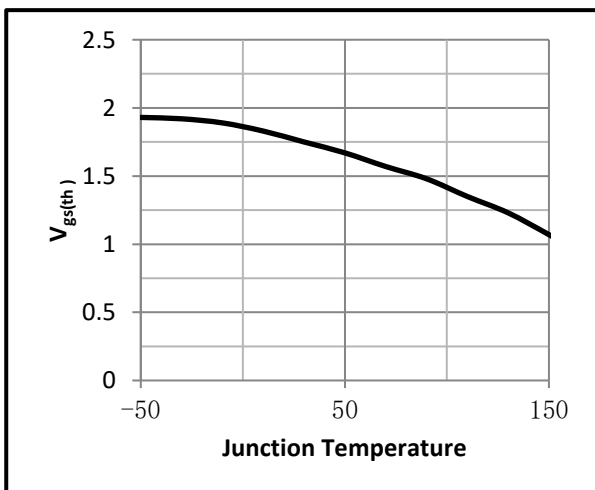


Fig.6 Resistance V.S Drain Current

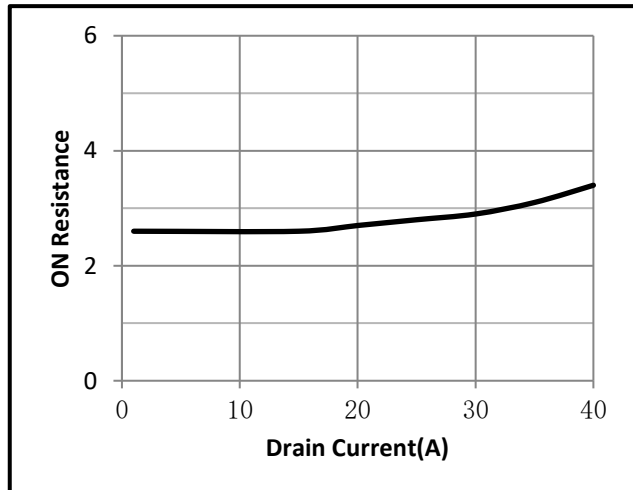


Fig.7 On-Resistance VS Gate Source Voltage

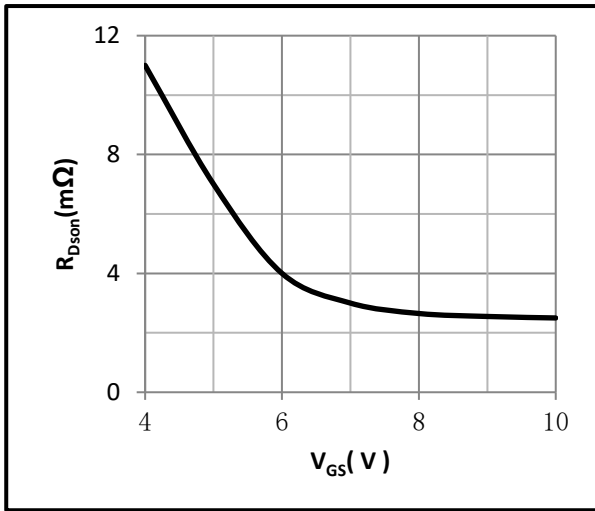


Fig.8 On-Resistance V.S Junction Temperature

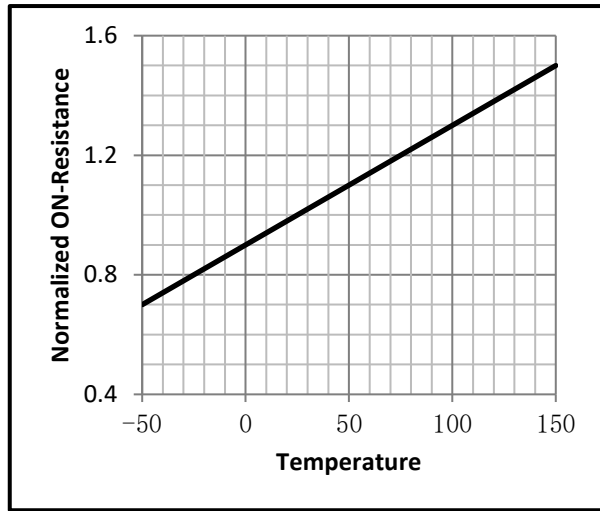


Fig.9 SOA Maximum Safe Operating Area

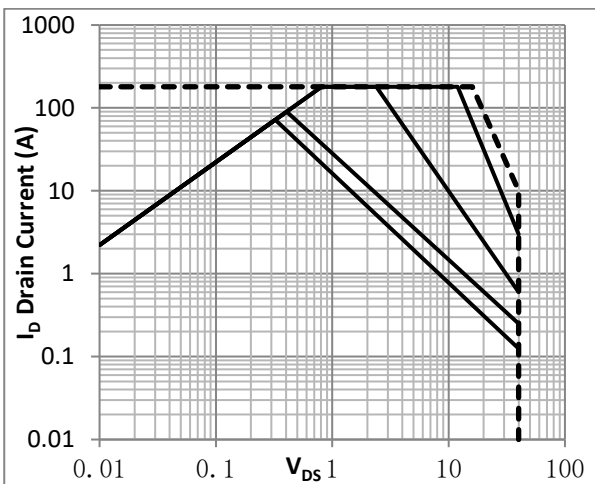


Fig.10 I_D -Junction Temperature

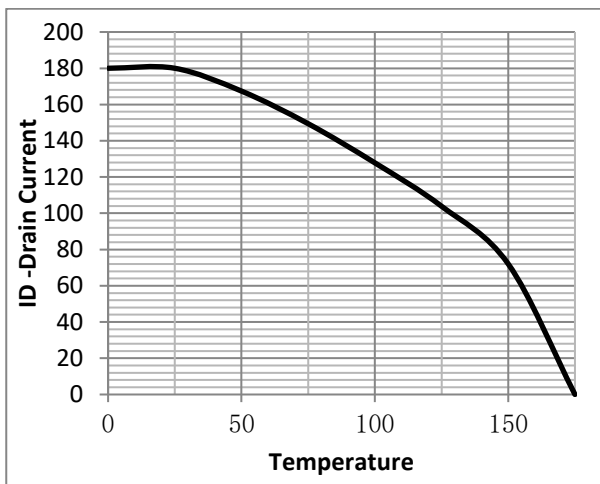


Fig.11 Switching Time Measurement Circuit

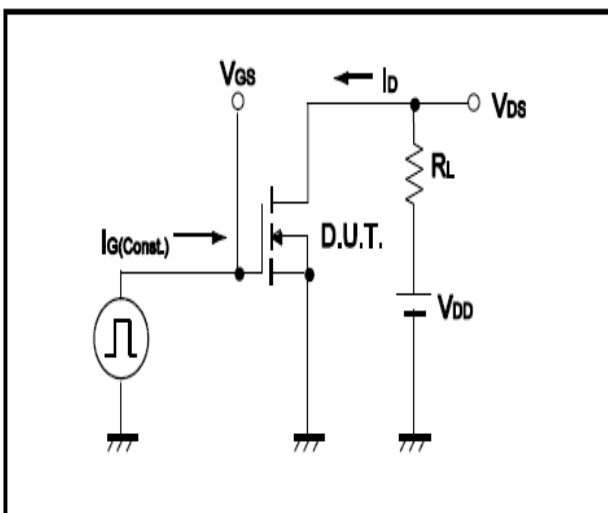


Fig.12 Gate Charge Waveform

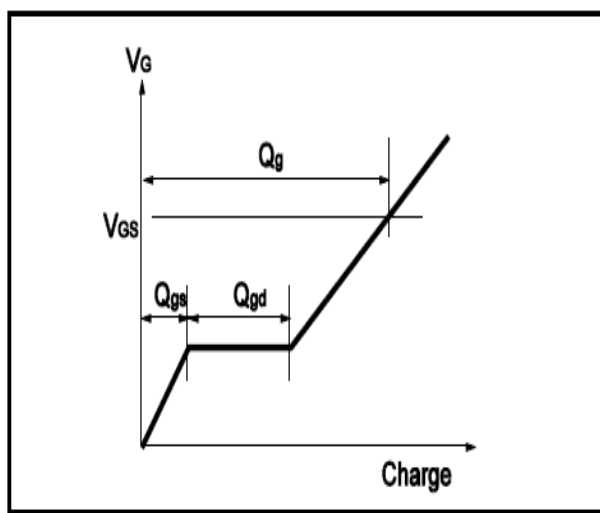


Fig.13 Resistive Switching Test Circuit

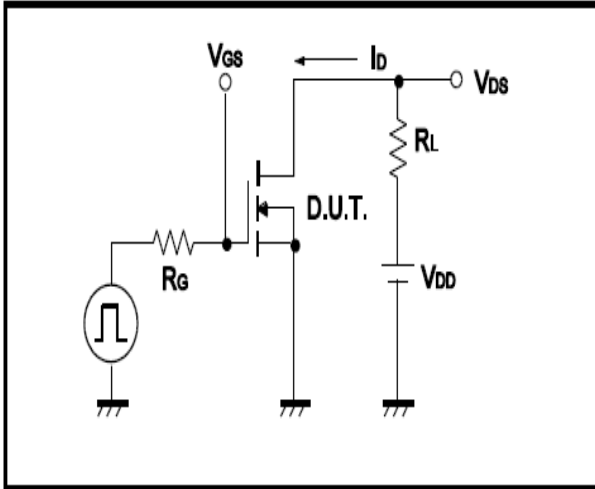
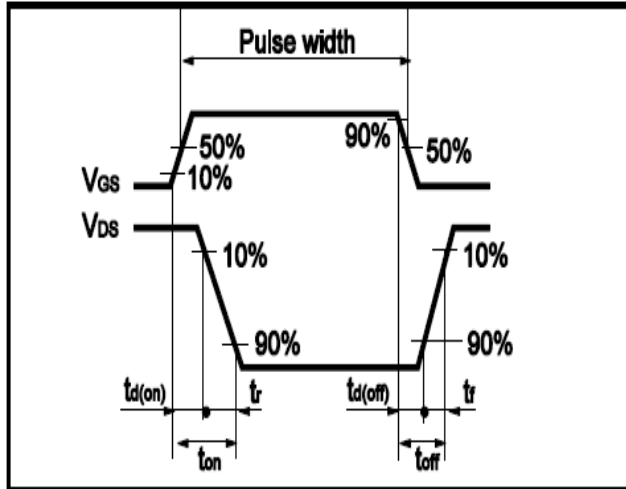


Fig.14 Resistive Switching Test Waveform





•Dimensions (TO-252)

Unit: mm

SYMBOL	min	max	SYMBOL	min	max
A	2.10	2.50	B	0.85	1.25
b	0.50	0.80	b1	0.50	0.90
b2	0.45	0.70	C	0.45	0.70
D	6.30	6.75	D1	5.10	5.50
E	5.30	6.30	e1	2.25	2.35
L1	9.20	10.60	e2	4.45	4.75
L2	0.90	1.75	L3	0.60	1.10
K	0.00	0.23			

